

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LEON ZHANG	05/29/2018
HENRY HAO FANG	05/29/2018
CHEN GONG	05/29/2018
LESTER MING ZHANG	05/29/2018
YONGLI WANG	05/29/2018
HUAN CHEN	05/29/2018
RECEIVING PARTY DATA	
Name:	EMC IP HOLDING COMPANY LLC
Street Address:	176 SOUTH STREET
City:	HOPKINTON
State/Country:	MASSACHUSETTS
Postal Code:	01748
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17096237
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	1003-877.001
NAME OF SUBMITTER:	DAVID E. HUANG, ESQ.
SIGNATURE:	/David E. Huang, Reg. No. 39,229/
DATE SIGNED:	12/30/2020
Total Attachments: 8	

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ASSIGNMENT

WHEREAS, we, Leon Zhang, Henry Hao Fang, Chen Gong, Lester Ming Zhang, Yongli Wang and Huan Chen, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled **METHOD AND DEVICE FOR DEPLICATION** (Application), the specification of which:

☐ is being executed on even date herewith and is about to be filed in the United States Patent Office;

☒ was filed on 11/12/2020 as U.S. Application No. 17/096,237

☐ was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the State of Delaware and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the

giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

AND, we hereby authorize our attorneys, EMC IP Holding Company LLC, to insert here in parenthesis (17/096,237 filed 11/12/2020) the application number and filing date of said Application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: May 29, 2018

Leon Zhang

Inventor's Signature

Print full name of inventor

Leon Zhang

2# 15 G, Jinxi Park, Shijichengiii

Residence

Beijing, China 100097

Citizenship

China (People's Republic)

Mailing Address

Same as above

I, Qiaosheng Zhou (name of first witness), whose residential address is
7F, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Leon Zhang** (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Qiaosheng Zhou (signature of first witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

I, Wilson Hu (name of second witness), whose residential address is
7F, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Leon Zhang** (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Wilson Hu (signature of second witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

Date: May 29, 2018

Henry Hao Fang
Inventor's Signature

Print full name of inventor

Henry Hao Fang

Residence

Room503, Unit 3, Building C16
Fulitaoyuan, Jancaichen East Rd
Beijing, China 100096

Citizenship

China (People's Republic)

Mailing Address

Same as above

I, Qiaosheng Zhou (name of first witness), whose residential address is
7F, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Henry Hao Fang** (name of person signing the assignment),
who is personally known to me, execute the above assignment.

Qiaosheng Zhou (signature of first witness)
Signed at 7F, Block D, Tsinghua Science Park, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

I, Wilson Hu (name of second witness), whose residential address is

was personally present and did see **Henry Hao Fang** (name of person signing the assignment),
who is personally known to me, execute the above assignment.

Wilson Hu (signature of second witness)
Signed at 7F, Block D, Tsinghua Science Park, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

Date: May 29, 2018

Chen Gong
Inventor's Signature

Print full name of inventor

Chen Gong

Residence

7-2-503 Jin Yu Hua Fu Long Yu Middle Road

Beijing, China 100083

Citizenship

China (People's Republic)

Mailing Address

Same as above

I, Qiaosheng Zhao (name of first witness), whose residential address is
7F, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Chen Gong** (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Qiaosheng Zhao (signature of first witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

I, Wilson Hu (name of second witness), whose residential address is
7F, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Chen Gong** (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Wilson Hu (signature of second witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

Date: May 29, 2018

Lester Zhang
Inventor's Signature

Print full name of inventor

Lester Ming Zhang

Residence

Wangjingyan, Wangjing Zhong Huan South

Beijing, China 100084

Citizenship

China (People's Republic)

Mailing Address

Same as above

I, Qiaosheng Zhou (name of first witness), whose residential address is 7F, Block D, Tsinghua Science Park, Haidian, Beijing was personally present and did see **Lester Ming Zhang** (name of person signing the assignment), who is personally known to me, execute the above assignment.

Qiaosheng Zhou (signature of first witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

I, Wilson Hu (name of second witness), whose residential address is _____ was personally present and did see **Lester Ming Zhang** (name of person signing the assignment), who is personally known to me, execute the above assignment.

Wilson Hu (signature of second witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

Date: May 29, 2018

Yongli Wang
Inventor's Signature

Print full name of inventor

Yongli Wang

Residence

Tsinghua Science Park

Beijing, China 100084

Citizenship

China (People's Republic)

Mailing Address

Same as above

I, Qiaosheng Zhao (name of first witness), whose residential address is
7F, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Yongli Wang** (name of person signing the assignment), who
is personally known to me, execute the above assignment.

Qiaosheng Zhao (signature of first witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

I, Wilson Hu (name of second witness), whose residential address is
7F, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Yongli Wang** (name of person signing the assignment), who
is personally known to me, execute the above assignment.

Wilson Hu (signature of second witness)
Signed at 7F, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

Date: May 29, 2018

Huan Chen.

Inventor's Signature

Print full name of inventor

Huan Chen

Residence

Building 5, Room 718,
4# South Fourth Street, Zhong Guan Cun
Beijing, China 100084

Citizenship

China (People's Republic)

Mailing Address

Same as above

I, Qiaosheng Zhou (name of first witness), whose residential address is
77, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Huan Chen** (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Qiaosheng Zhou (signature of first witness)
Signed at 77, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).

I, Wilson Hu (name of second witness), whose residential address is
77, Block D, Tsinghua Science Park, Haidian, Beijing
was personally present and did see **Huan Chen** (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Wilson Hu (signature of second witness)
Signed at 77, Block D, Tsinghua Science Park, Haidian, Beijing (location of witness signature)
on this day, May 29, 2018 (date of signature).